Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	18
Terminal Finish	100Sn
MS Number	MS011558A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.05 E-01	86.20	862000	61.68	616784
Thermosets	Epoxy resin	Proprietary	2.66 E-02	7.50	75000	5.37	53665
Thermosets	Phenol Novolac	9003-35-4	1.42 E-02	4.00	40000	2.86	28621
Other inorganic materials	Antimony Trioxide	1309-64-4	5.31 E-03	1.50	15000	1.07	10733
Thermosets	Brominated Resin	40039-93-8	1.77 E-03	0.50	5000	0.36	3578
Other inorganic materials	Carbon Black	1333-86-4	1.06 E-03	0.30	3000	0.21	2147
Subtotal			3.54 E-01	100	1000000	71.55	715527

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.26 E-01	97.57	975706	25.50	254961
Copper & its alloys	Iron	7439-89-6	2.95 E-03	2.28	22789	0.60	5955
Copper & its alloys	Zinc	7440-66-6	1.63 E-04	0.13	1263	0.03	330
Copper & its alloys	Phosphorus	7723-14-0	3.14 E-05	0.02	242	0.01	63
Subtotal			1.29 E-01	100.00	1000000	26.13	261309

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.72 E-04	100.0	1000000	0.20	1964

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.34 E-03	100.0	1000000	0.67	6743

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.71 E-04	99.99	1000000	0.12	1154

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.78 E-03	100.0	1000000	0.97	9659

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.44 E-03	80	800000	0.29	2916
Thermosets	Epoxy Resin	Proprietary	2.71 E-04	15	150000	0.05	547
Others	Curing agent & hardener	Proprietary	9.02 E-05	5	50000	0.02	182
Subtotal			1.80 E-03	100	1000000	0.36	3645

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.95 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	18
Terminal Finish	SnPb
MS Number	MS011556A

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.05 E-01	86.20	862000	61.68	616784
Thermosets	Epoxy resin	Proprietary	2.66 E-02	7.50	75000	5.37	53665
Thermosets	Phenol Novolac	9003-35-4	1.42 E-02	4.00	40000	2.86	28621
Other inorganic materials	Antimony Trioxide	1309-64-4	5.31 E-03	1.50	15000	1.07	10733
Thermosets	Brominated Resin	40039-93-8	1.77 E-03	0.50	5000	0.36	3578
Other inorganic materials	Carbon Black	1333-86-4	1.06 E-03	0.30	3000	0.21	2147
Subtotal			3.54 E-01	100	1000000	71.55	715527

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.26 E-01	97.57	975706	25.50	254961
Copper & its alloys	Iron	7439-89-6	2.95 E-03	2.28	22789	0.60	5955
Copper & its alloys	Zinc	7440-66-6	1.63 E-04	0.13	1263	0.03	330
Copper & its alloys	Phosphorus	7723-14-0	3.14 E-05	0.02	242	0.01	63
Subtotal			1.29 E-01	100.00	1000000	26.13	261309

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.72 E-04	100.0	1000000	0.20	1964

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.84 E-03	85.0	850000	0.57	5731
Tin & its alloys	Lead	7439-92-1	5.01 E-04	15.0	150000	0.10	1011
Subtotal			3.34 E-03	100.0	1000000	0.67	6743

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.71 E-04	99.99	1000000	0.12	1154

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.78 E-03	100.0	1000000	0.97	9659

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.44 E-03	80	800000	0.29	2916
Thermosets	Epoxy Resin	Proprietary	2.71 E-04	15	150000	0.05	547
Others	Curing agent & hardener	Proprietary	9.02 E-05	5	50000	0.02	182
Subtotal			1.80 E-03	100	1000000	0.36	3645

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.95 E-01**	**100.00**	**1000000**

ANALOG DEVICES